



ANDS4E38C

InGaAIP Ultra Bright Red Light Emission T-1 3/4 Package (5 mm)

Features

- Peak wavelength ($\lambda p = 632 \text{ nm}$) ultra bright emission
- All plastic mold type, clear colorless lens
- Low drive current: 1 to 20 mA DC
- Excellent On-Off contrast ratio
- Fast response time, capable of pulse operation
- High power luminous intensity
- Suitable for Outdoor Message Signboards
- High reliability, storage temperature -40 to +120°C

Maximum Ratings (T = 25°C)

Characteristics	Symbol	Rating	Unit	
Forward Current	I _F	50	mA	
Reverse Voltage	V _R	4	V	
Power Dissipation	P _D	125	mW	
Operating Temperature Range*	T _{Opr}	-40 to 85	°C	
Storage Temperature Range	T _{Stg}	-40 to 120	°C	

^{*} At constant current

Electro-Optical Characteristics (T = 25°C)

Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V _F	I _F = 20 mA	-	2.1	2.5	V
Reverse Current	I _R	V _R = 4 V	-	-	50	μA
Luminous Intensity	I _V	I _F = 20 mA	2,200	4,200	-	mcd
Peak Emission Wavelength	l _P	I _F = 20 mA	-	632	-	nm
Spectral Line Half Width	Δλ	I _F = 20 mA	-	15	-	nm
Dominant Wavelength	λd	I _F = 20 mA	-	622	-	nm
Full Viewing Angle	θ	I _V = 1/2 Peak	-	17	-	degree

Precaution

Please be careful of the following:

- 1. Soldering temperature: 260°C max
 - Soldering time: 3 sec. max
 - Soldering portion of lead: up to 2 mm from the body of the device
- 2. The lead can be formed up to 5 mm from the body of the device without forming stress. Soldering should be performed after the lead forming.

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